



ATTACHMENT FOR CLAIM AMENDMENTS

The following is a marked up version of each amended claim in which underlines indicates insertions and brackets indicate deletions.

1. (Twice Amended) A manufacturing method for manufacturing an electro-optical device having an electro-optical panel with a substrate holding an electro-optical material and a mount base member bonded to the substrate, the manufacturing method comprising:

a first step of aligning the substrate with the mount base member so that a plurality of first alignment marks, which are formed on the surface of the substrate and arranged to be opposed to each other with a first terminal bank interposed therebetween, is aligned with a plurality of second alignment marks, which are formed on the surface of the mount base member and arranged to be opposed to each other with a second terminal bank interposed therebetween, the first terminal bank being formed on the surface of the substrate, the second terminal bank being formed on the surface of the mount base member at a pitch which is smaller than a pitch of the first terminal bank, the plurality of second alignment marks being arranged at a spacing approximately equal to a spacing of the plurality of first alignment marks; and

a second step of connecting [a] the first terminal bank[, formed on the surface of the substrate,] to [a] the second terminal bank [formed on the surface of the mount base member at a pitch different from a pitch of the first terminal

bank when the substrate is bonded to the mount base member] with thermal compression bonding, the mount base member having a linear thermal expansion coefficient that is larger than a linear thermal expansion coefficient of the substrate;

wherein the connection step directly connects the first terminal bank and the second terminal bank, both of which [such that the pitch of the first terminal bank and the pitch of the second terminal bank] become substantially equal to each other in pitch when the substrate and the mount base member are deformed during the thermal compression bonding of the substrate and the mount base member, and wherein during the connection step, the plurality of second alignment marks become spaced mutually more apart than the spacing of the first alignment marks.

9. (Twice Amended) A terminal connection method for connecting a first terminal bank formed on the surface of a first base member to a second terminal bank formed on the surface of a second base member, the connection method comprising the steps of:

fabricating the second terminal bank at a pitch that is smaller than [different from] a pitch of the first terminal bank, the second base member having a linear thermal expansion coefficient that is larger than a linear thermal expansion coefficient of the first base member; [and]

aligning the first bank member with the second base member so that a plurality of first alignment marks, which are formed on the surface of the first

bank member and arranged to be opposed to each other with the first terminal bank interposed therebetween, is aligned with a plurality of second alignment marks, which are formed on the surface of the second base member and arranged to be opposed to each other with the second terminal bank interposed therebetween, the plurality of second alignment marks being arranged at a spacing approximately equal to a spacing of the plurality of first alignment marks;

directly connecting the first terminal bank and the second terminal bank;
thermal compression bonding the first base member to the second base member; and

during the thermal compression bonding step, deforming the first base member and the second base member such that the [pitch of the] first terminal bank and [the pitch of] the second terminal bank become substantially equal in pitch and the plurality of second alignment marks become spaced mutually more apart than the spacing of the first alignment marks.

14. (Amended) An electro-optical device comprising:
 - an electro-optical panel including a substrate holding an electro-optical material;
 - a mount base member thermal-bonded to the substrate, said mount base member having a linear thermal expansion coefficient that is larger than a linear thermal expansion coefficient of the substrate;
 - a first terminal bank formed on the surface of the substrate;

a plurality of first alignment marks formed and mutually spaced apart on the surface of the substrate;

a second terminal bank formed [and mutually spaced apart] on the mount base member, wherein the second terminal bank is directly connected to the first terminal bank, [at] a pitch of the second terminal bank being [thereof] substantially equal to [the] a pitch of the first terminal bank; and

a plurality of second alignment marks formed on the surface of the mount base member, and spaced mutually more apart than the spacing of the first alignment marks,

wherein one group of the plurality of first alignment marks and another group of the plurality of first alignment marks are arranged to be opposed to each other with the first terminal bank interposed therebetween, and

wherein one group of the plurality of second alignment marks and another group of the plurality of second alignment marks are arranged to be opposed to each other with the second terminal bank interposed therebetween.

23. (Amended) A mount base member to be bonded to a substrate of an electro-optical panel, comprising:

a second terminal bank formed at a pitch that is smaller than [different from] a pitch of a first terminal bank formed on the substrate, [and] the second terminal bank being directly connectable [connected] to the first terminal bank;

a linear thermal expansion coefficient that is larger than a linear thermal expansion coefficient of the substrate; and

a plurality of second alignment marks arranged to be opposed to each other with the second terminal bank interposed therebetween, the plurality of second alignment marks being arranged at a spacing approximately equal to a spacing of a plurality of first alignment marks formed on the substrate, the plurality of first alignment marks being arranged to be opposed to each other with the first terminal bank interposed therebetween;

wherein after the mount member is connected to the substrate with thermal compression bonding, the plurality of second alignment marks are spaced mutually more apart than the spacing of the first alignment marks.